

# **ABSTRACT**

1           A method for depositing a solder layer or solder bump on a sloped surface. The  
2 method includes etching a sloped surface on a planar semiconductor substrate, depositing  
3 a solder-wettable layer on the sloped surface, masking the wettable layer with a coating  
4 layer to control the position of the solder deposition, and using an organic film to prevent  
5 the solder from being deposited at regions not above either the wettable layer or the  
6 coating layer. Also, a semiconductor device structure on which a solder layer or solder  
7 bump is formed exclusively on a sloped surface.